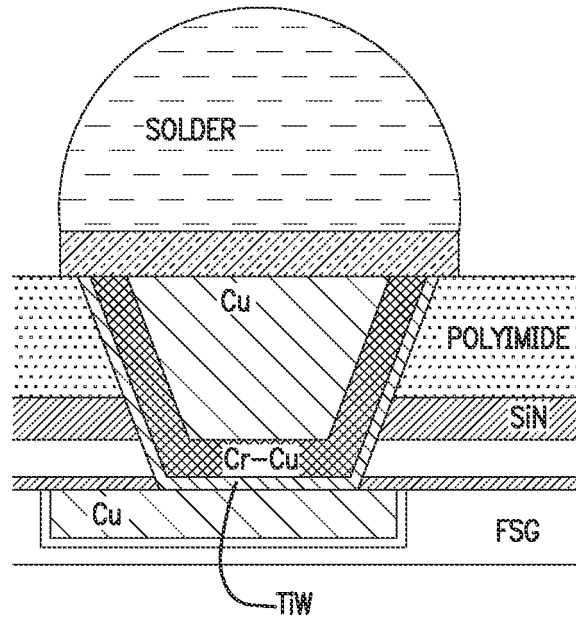
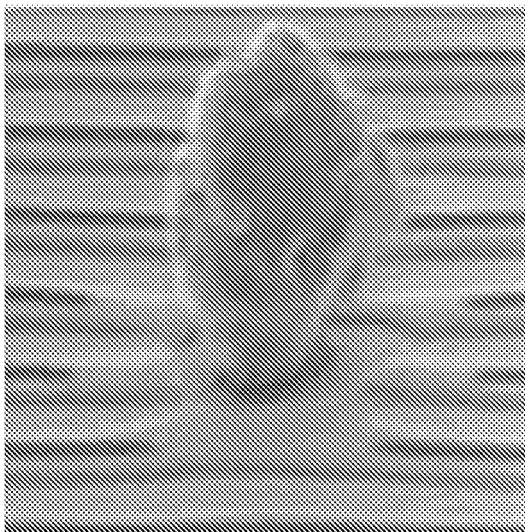


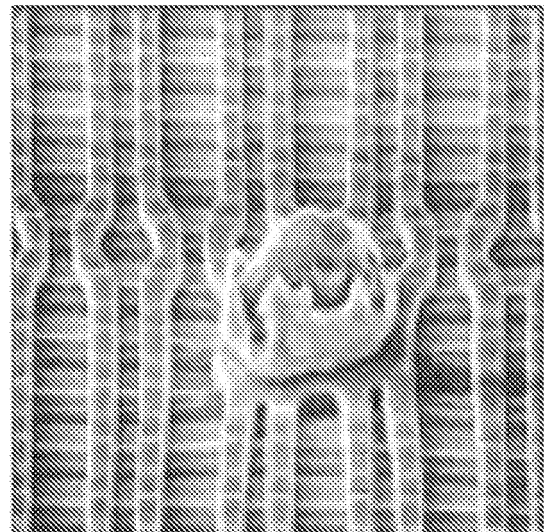
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WTi diffusion/ adhesion layer in solder bump process.

FIG. 1

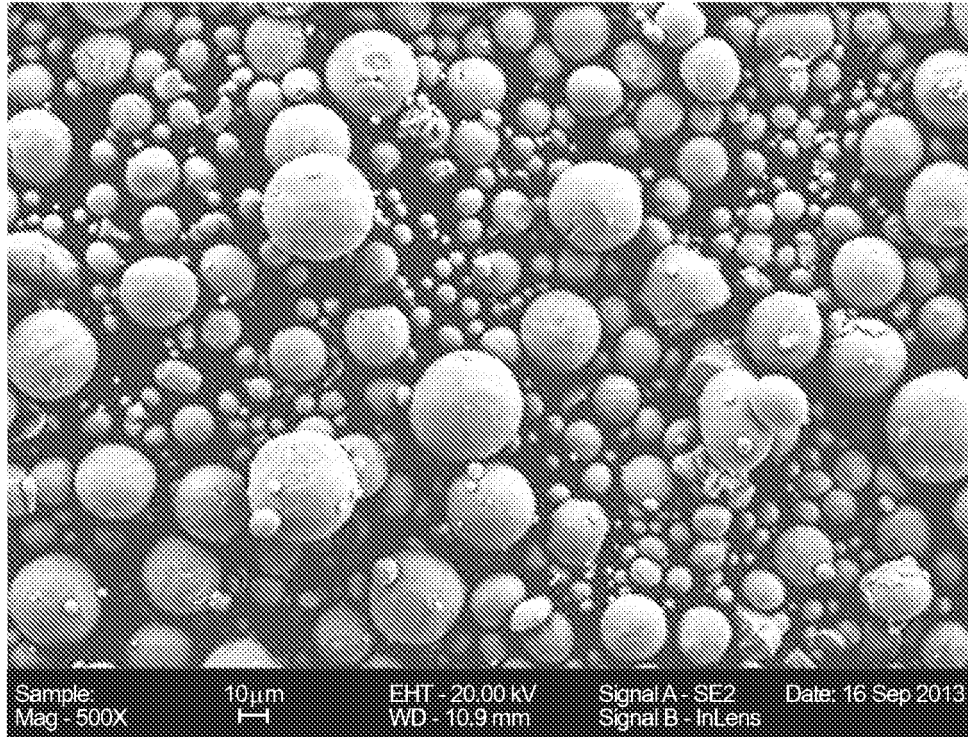
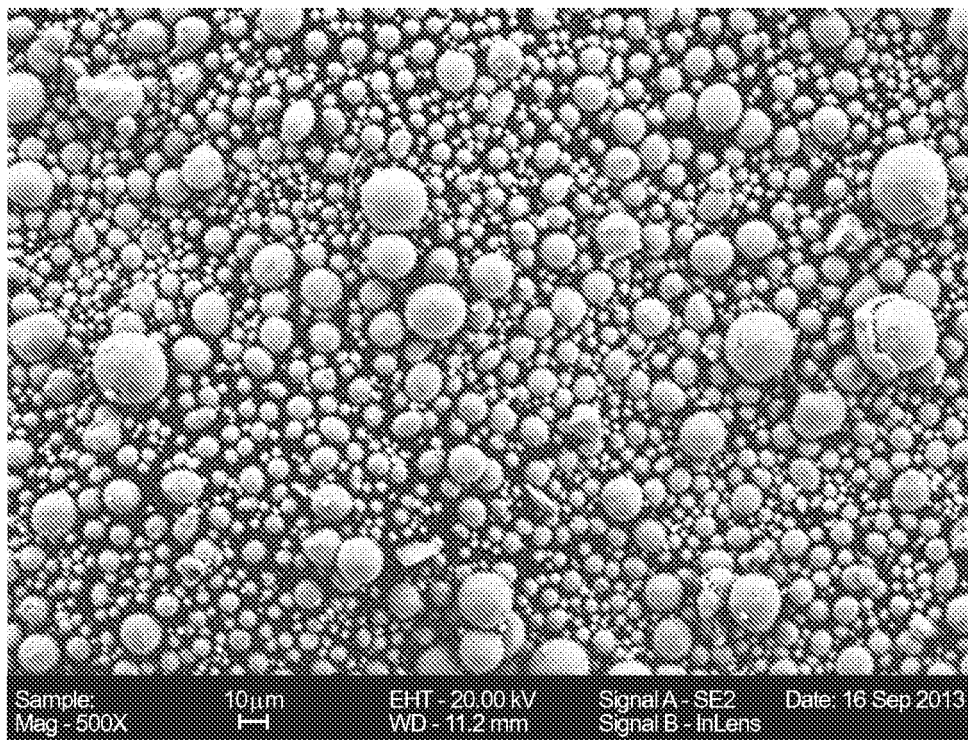
Defect Causing an Open
A large, non-conducting defect
opens up three wires in the circuit

FIG. 2

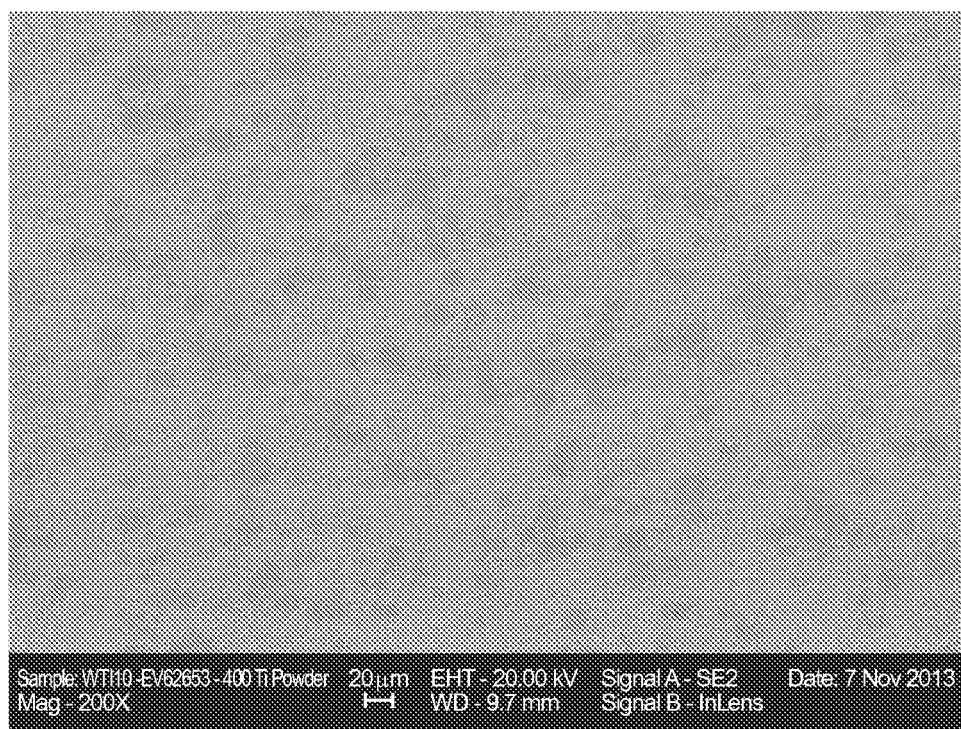
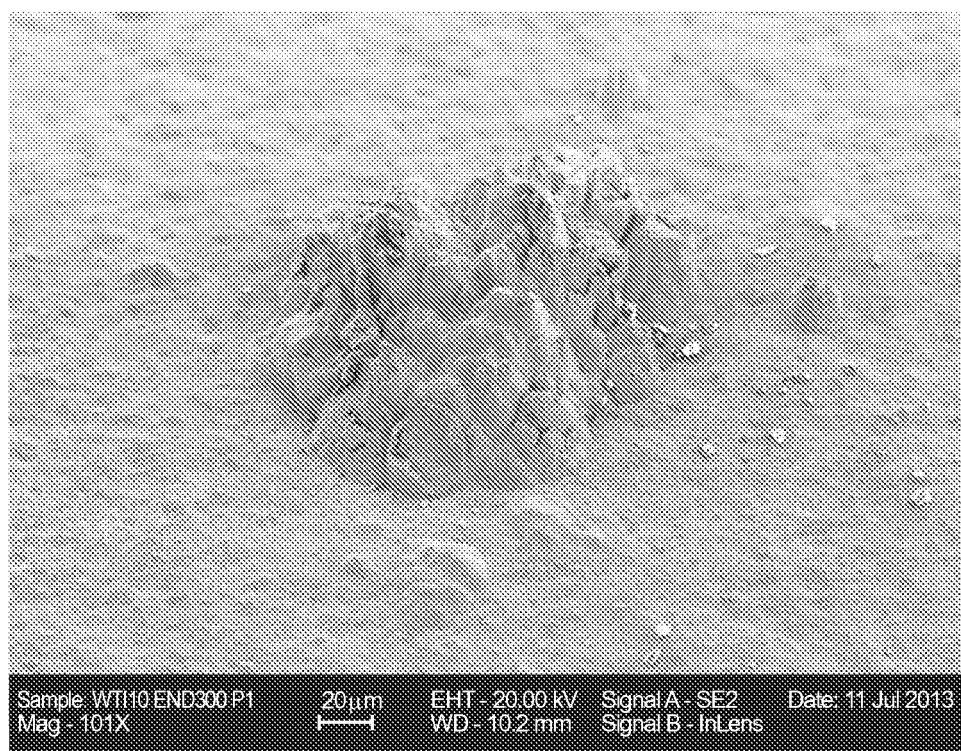
Defect Causing a Short
A large, conducting defect shorts
cut four wires in the circuit

FIG. 3

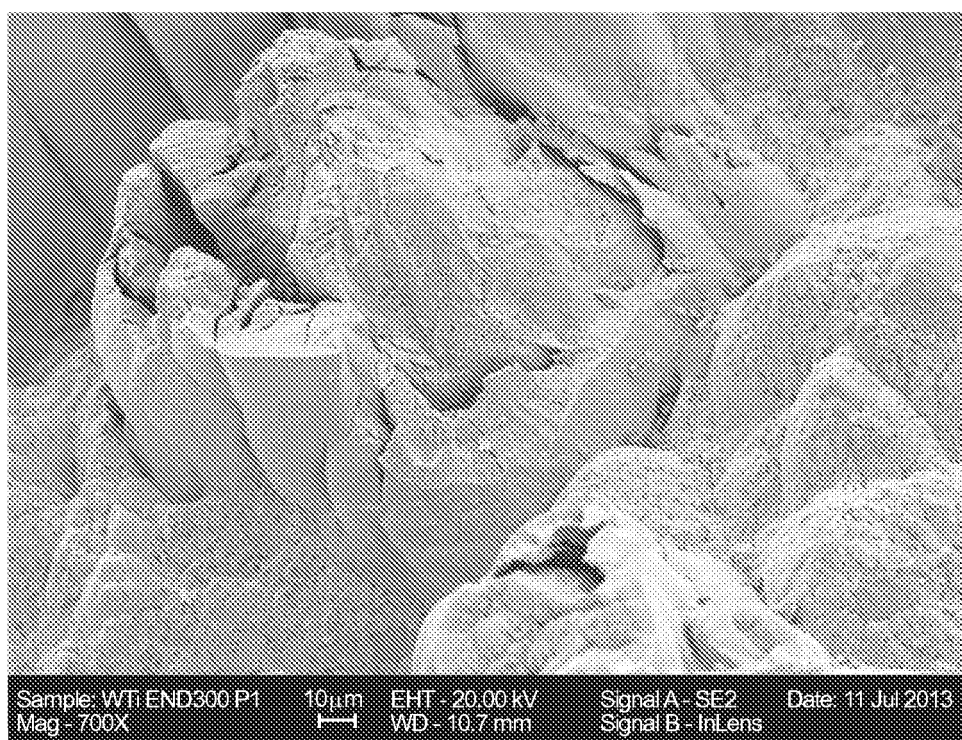
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**FIG. 4****FIG. 5**

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**FIG. 6****FIG. 7**

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**FIG. 8**

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Present target

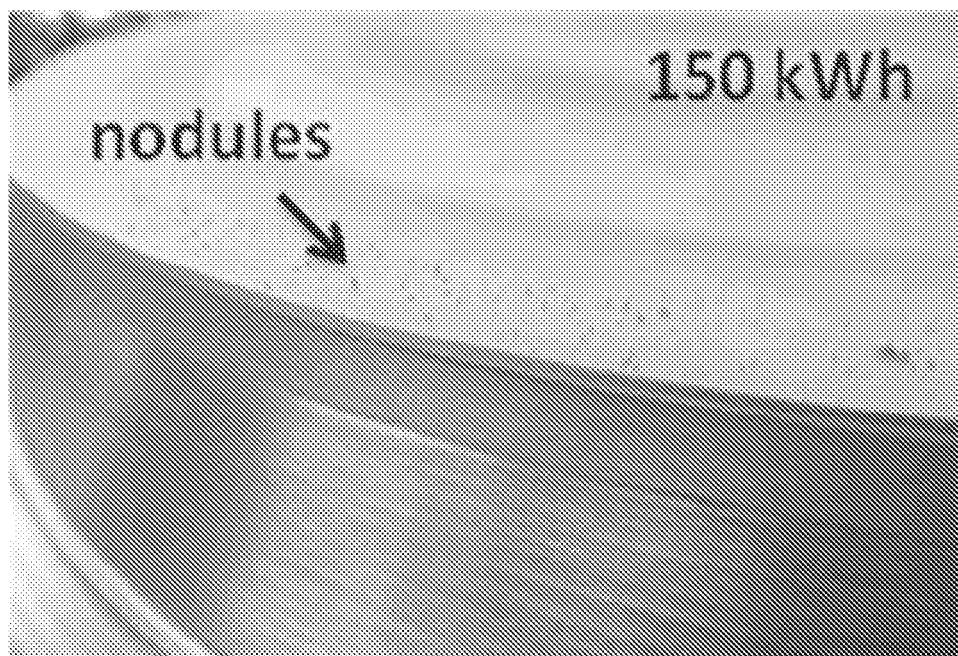


FIG. 9

New invented target

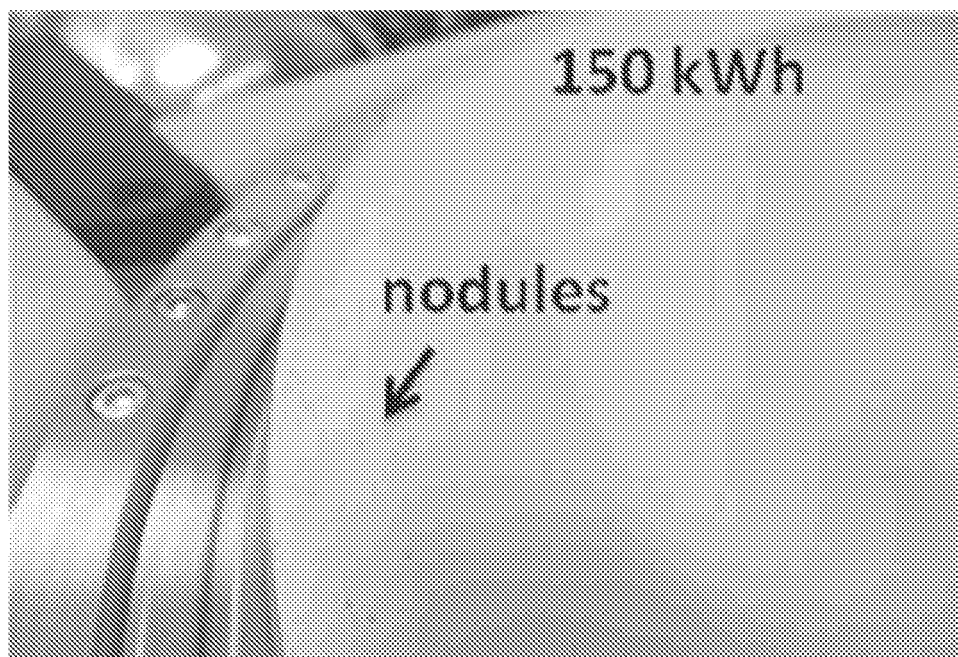


FIG. 10